

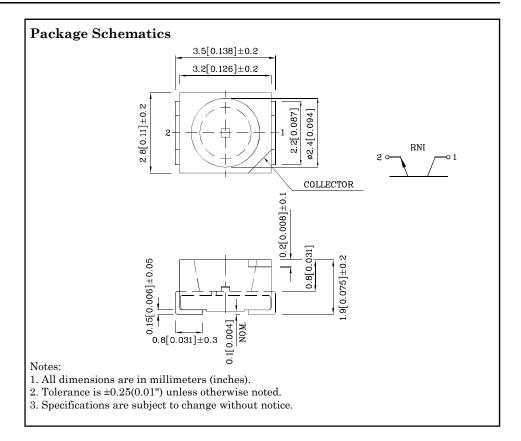


### **Features**

- Long life and robust package
- Standard Package: 2000pcs/ Reel
- $\bullet$  MSL (Moisture Sensitivity Level): 3
- RoHS compliant







## Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Condiction
VBR CEO	Collector-to-Emitter Breakdown Voltage	30			V	Ic=100μA Ee=0mW/cm²
VBR ECO	Emitter-to-Collector Breakdown Voltage	5			V	Ie=100μA Ee=0mW/cm²
VCE(SAT)	Collector-to-Emitter Saturation Voltage			0.8	V	IC=2mA Ee=20mW/cm <sup>2</sup>
ICEO	Collector Dark Current			100	nA	VCE=10V Ee=0mW/cm <sup>2</sup>
TR	Rise Time (10% to 90%)		15		μs	V <sub>CE</sub> =5V I <sub>C</sub> =1mA R <sub>L</sub> =1KΩ
TF	Fall Time (90% to 10%)		15		μs	
I(ON)	On State Collector Current	0.2	0.4		mA	$V_{\text{CE}}$ =5 $V$ $E_{\text{e}}$ =1 $m$ $W$ /c $m$ <sup>2</sup> $\lambda$ =940 $n$ $m$

## Absolute Maximum Ratings at TA=25°C

Absolute Maximum Ratings at 1A-25 C				
Parameter	Maximum Ratings			
Collector-to-Emitter Voltage	30V			
Emitter-to-Collector Voltage	5V			
Power Dissipation at (or below) 25°C Free Air Temperature	100mW			
Operating / Storage Temperature Range	-40°C To +85°C			

A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)



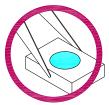
3.5x2.8mm PHOTOTRANSISTOR

### **Handling Precautions**

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

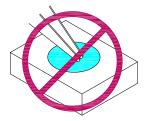
As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.

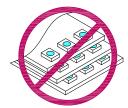


2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.

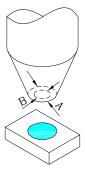




3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



- 4.1. The inner diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks.
- 4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



5. As silicone encapsulation is permeable to gases, some corrosive substances such as H<sub>2</sub>S might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

Oct 12, 2016 XDSB5591 V3 Layout: Maggie L.





Typical Electro-Optical Characteristics Curves

 $\begin{tabular}{ll} Fig. 1 & Collector & Power Dissipation & vs. \\ & Ambient Temperature & \\ \end{tabular}$ 

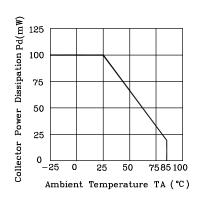


Fig.2 Spectral Sensitivity

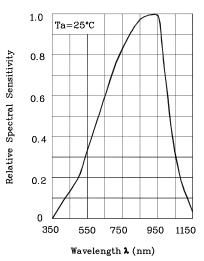


Fig.3 Relative Collector Current vs.
Ambient Temperature

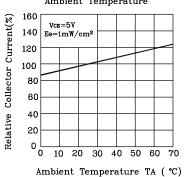


Fig.4 Collector Current Ic=f(Ec), Vce=5V, Ta=25°C

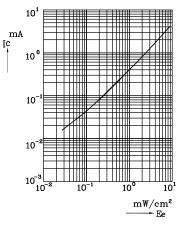


Fig.5 Collector Dark Current vs.
AmbientTemperature

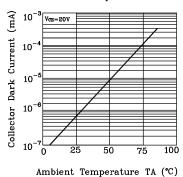
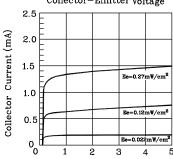


Fig. 6 CollectorCurrent vs.
Collector-Emitter Voltage

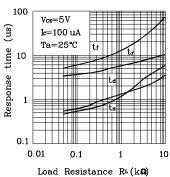


Collector-Emitter Voltage VCE (V)

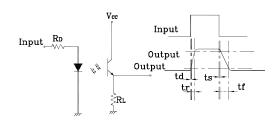




Fig.7 Response Time vs. Load Resistance

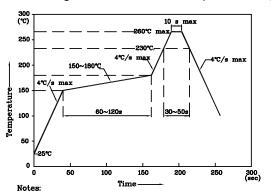


Test Circuit for Response Time



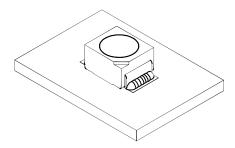
❖ LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)

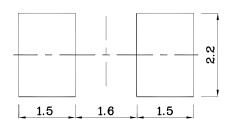


- 1. Maximum soldering temperature should not exceed 260°C
- 2. Recommended reflow temperature:  $145^{\circ}C-260^{\circ}C$
- Do not put stress to the epoxy resin during high temperatures conditions

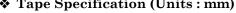
**❖** The device has a single mounting surface. The device must be mounted according to the specifications.

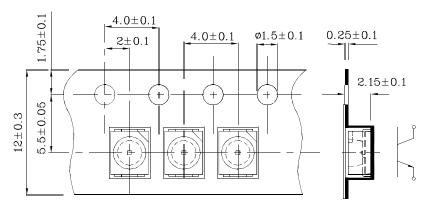


Recommended Soldering Pattern (Units: mm; Tolerance:  $\pm 0.1$ )



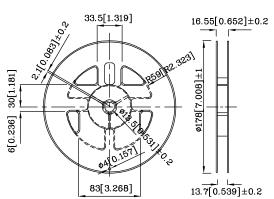
**❖** Tape Specification (Units: mm)





TAPE

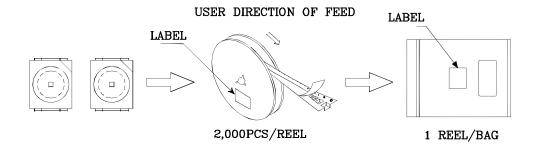
# **❖** Reel Dimension

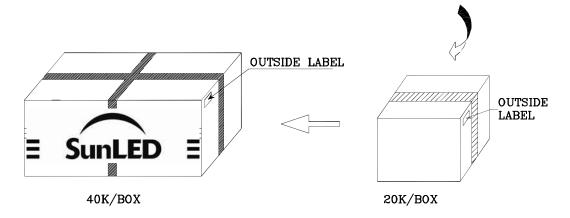


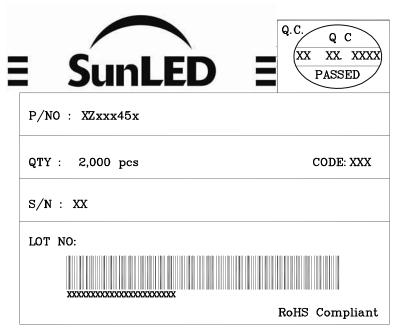




#### PACKING & LABEL SPECIFICATIONS







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